

I CLAIM:

1. A conductive bump for a semiconductor chip that has a pad-mounting surface which is provided with at least a bonding pad thereon, said conductive bump comprising:

5 a first metal layer adapted to be bonded to the bonding pad;

a conductive paste body formed on said first metal layer; and

10 a second metal layer formed on said paste body such that said paste body is sandwiched between said first and second metal layers.

2. The conductive bump of Claim 1, wherein said first metal layer has a base portion bonded to said bonding pad, and a peripheral portion extending from said base portion in a transverse direction relative to said base portion and cooperating with said base portion to confine a recess therebetween, said conductive paste body filling said recess, said recess being 20 closed by said second metal layer.

3. A method for forming a conductive bump on a semiconductor chip having a pad-mounting surface provided with at least a bonding pad thereon, said method comprising the steps of:

25 forming a photoresist layer that is adapted to be bonded to the pad-mounting surface;

forming a through-hole in said photoresist

layer to expose said bonding pad therefrom;

forming a first metal layer that is adapted to be bonded to the bonding pad within said through-hole;

5 filling said through-hole with a conductive paste to form a paste body on said first metal layer; and

10 forming a second metal layer on said paste body such that said paste body is sandwiched between and is enclosed by said first and second metal layers.

4. The method of Claim 3, wherein said first metal layer has a base portion that is adapted to be bonded to the bonding pad, and a peripheral portion extending from said base portion in a transverse direction 15 relative to said base portion and cooperating with said base portion to confine a recess therebetween, said second metal layer being connected to said first metal layer and closing said recess in such a manner that said paste body is enclosed by said first and 20 second metal layers.